

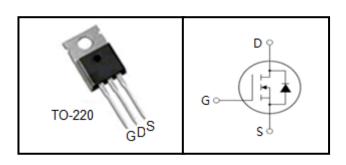
100V N-Channel Trench MOSFET

FEATURES

- High Density Cell Design for Ultra Low Rdson
- Fully Characterized Avalanche Voltage and Current
- Good Stability with High E_{AS}
- Excellent Package for Good Heat Dissipation

APPLICATIONS

- Power Switching Application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply





| Device Marking and Package Information | | | |
|--|---------|---------|--|
| Device | Package | Marking | |
| TMP140N10A | TO-220 | 140N10A | |

| Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted | | | | |
|--|-----------------------------------|----------|------|--|
| Parameter | Symbol | Value | Unit | |
| Drain-Source Voltage (V _{GS} = 0V) | V _{DSS} | 100 | V | |
| Continuous Drain Current (Package Limited) | I _D | 130 | Α | |
| Pulsed Drain Current (note1) | I _{DM} | 520 | Α | |
| Gate-Source Voltage | V _{GSS} | ±20 | ٧ | |
| Single Pulse Avalanche Energy (note2) | E _{AS} | 1300 | mJ | |
| Avalanche Current (note1) | I _{AS} | 70 | Α | |
| Power Dissipation (T _C = 25°C) | P_{D} | 235 | W | |
| Operating Junction and Storage Temperature Range | T _J , T _{stg} | -55~+150 | °C | |

| Thermal Resistance | | | | |
|---|-------------------|-------|------|--|
| Parameter | Symbol | Value | Unit | |
| Thermal Resistance, Junction-to-Case | R _{thJC} | 0.64 | 000 | |
| Thermal Resistance, Junction-to-Ambient | R _{thJA} | 62.5 | °C/W | |



| Specifications T _J = 25°C, unless otherwise noted | | | | | | | |
|--|-----------------------------|--|-------|------|------|------|--|
| | | | Value | | | | |
| Parameter | eter Symbol Test Conditions | | Min. | Тур. | Max. | Unit | |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | $V_{GS} = 0V, I_D = 250\mu A$ | 100 | | | V | |
| Zero Gate Voltage Drain Current | | $V_{DS} = 100V, V_{GS} = 0V, T_{J} = 25^{\circ}C$ | | | 1 | μΑ | |
| Zero Gate Voltage Drain Gurrent | I _{DSS} | $V_{DS} = 100V, V_{GS} = 0V, T_{J} = 150^{\circ}C$ | | | 100 | | |
| Gate-Source Leakage | I _{GSS} | $V_{GS} = \pm 20V$ | | | ±100 | nA | |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | 2 | | 4 | V | |
| Drain-Source On-Resistance (Note3) | R _{DS(on)} | $V_{GS} = 10V, I_{D} = 30A$ | | 6.0 | 7.0 | mΩ | |
| Forward Transconductance (Note3) | g_{fs} | $V_{DS} = 5V, I_{D} = 20A$ | 50 | | | S | |
| Dynamic | | | | | | | |
| Input Capacitance | C _{iss} | $V_{GS} = 0V$, | | 6320 | | pF | |
| Output Capacitance | C _{oss} | $V_{DS} = 25V$, | | 540 | | | |
| Reverse Transfer Capacitance | C _{rss} | f = 1.0MHz | | 359 | | | |
| Total Gate Charge | Q_g | | | 146 | | nC | |
| Gate-Source Charge | Q_{gs} | $V_{DD} = 50V, I_{D} = 20A, V_{GS} = 10V$ | | 27 | | | |
| Gate-Drain Charge | Q_{gd} | 63 | | 54 | | | |
| Turn-on Delay Time | t _{d(on)} | | | 31.5 | | | |
| Turn-on Rise Time | t _r | $V_{DD} = 50V, I_{D} = 2A,$ | | 33 | | ns | |
| Turn-off Delay Time | t _{d(off)} | $R_G = 2.5\Omega$ | | 46 | | | |
| Turn-off Fall Time | t _f | | | 17.5 | | | |
| Drain-Source Body Diode Characteris | stics | | | | | | |
| Continuous Body Diode Current | Is | T 0500 | | | 140 | ۸ | |
| Pulsed Diode Forward Current | I _{SM} | T _C = 25°C | | | 560 | А | |
| Body Diode Voltage | V _{SD} | $T_J = 25^{\circ}C$, $I_{SD} = 20A$, $V_{GS} = 0V$ | | | 1.2 | V | |
| Reverse Recovery Time | t _{rr} | I _F = 20A, | | 51 | | ns | |
| Reverse Recovery Charge | Q _{rr} | $di_F/dt = 500A/\mu s$ | | 61 | | nC | |

Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. I_{AS} = 70A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 1%



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

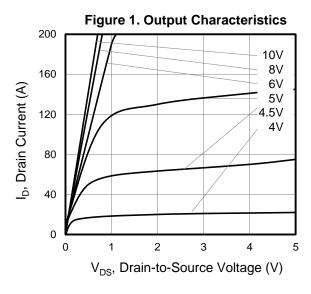


Figure 3. On-Resistance vs. Drain Current

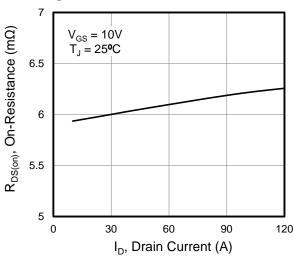


Figure 5. Gate Charge

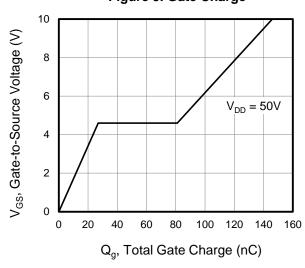


Figure 2. Transfer Characteristics $V_{DS} = 5V$ $V_{DS} = 5V$

Figure 4. Capacitance

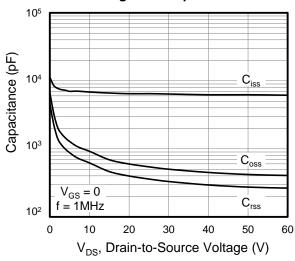
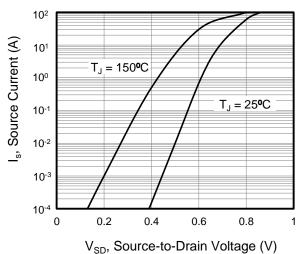


Figure 6. Body Diode Forward Voltage





Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 7. On-Resistance vs.

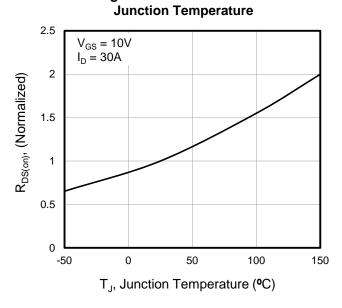


Figure 8. Threshold Voltage vs. Junction Temperature

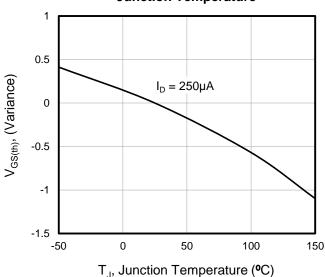


Figure 9. Transient Thermal Impedance

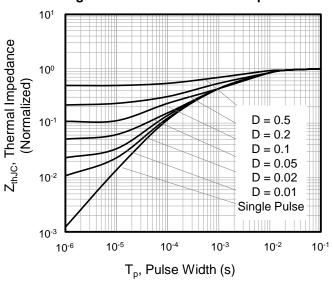




Figure A: Gate Charge Test Circuit and Waveform

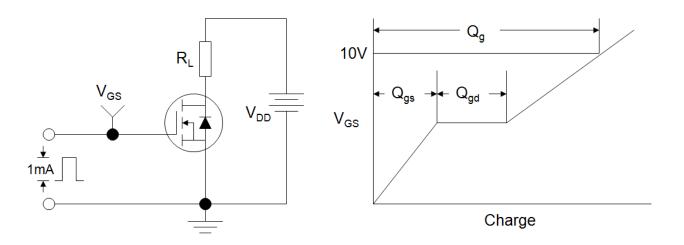


Figure B: Resistive Switching Test Circuit and Waveform

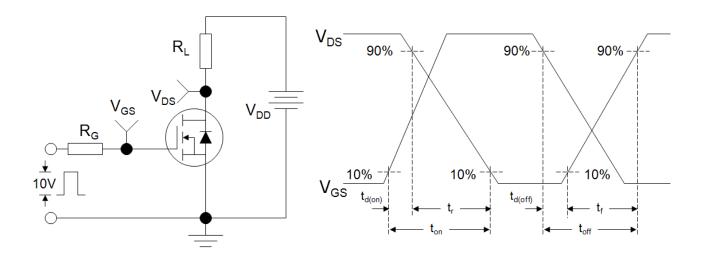
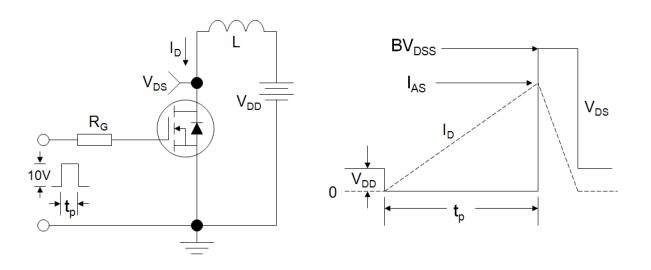
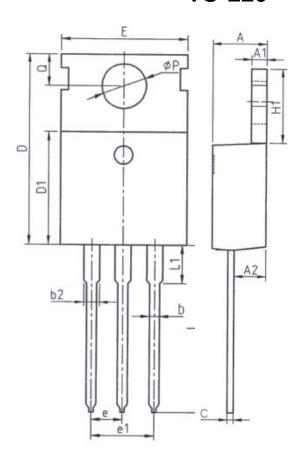


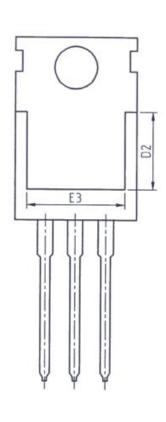
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-220





| Unit: mm | | | | |
|----------|--------|--------|--|--|
| Symbol | Min. | Max. | | |
| Α | 4. 37 | 4. 77 | | |
| A1 | 1. 25 | 1. 45 | | |
| A2 | 2. 20 | 2. 60 | | |
| b | 0. 70 | 0. 95 | | |
| b2 | 1. 17 | 1. 47 | | |
| С | 0. 40 | 0. 65 | | |
| D | 15. 10 | 16. 10 | | |
| D1 | 8. 80 | 9. 40 | | |
| D2 | 5. 50 | _ | | |

| Unit: mm | | | |
|----------|----------|--------|--|
| Symbol | Min. | Max. | |
| E | 9. 70 | 10. 30 | |
| E3 | 7. 00 | ı | |
| е | 2. 54BSC | | |
| e1 | 5. 08BSC | | |
| H1 | 6. 25 | 6. 85 | |
| L | 12. 75 | 13.80 | |
| L1 | - | 3. 40 | |
| Р | 3. 40 | 3. 80 | |
| Q | 2. 60 | 3. 00 | |



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